# **SKKD 115F**



# SEMIPACK<sup>®</sup> 1

## Fast Diode Modules

#### SKKD 115F

## Features

- Heat transfer through ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E 63 532

### **Typical Applications**

- Self-commutated inverters
- DC choppers
- AC motor speed control
- Inductive heating
- Uninterruptible power supplies
- Electronic welders
- General power switching
  applications

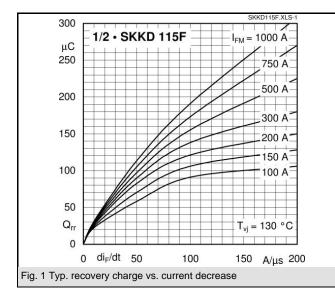
V <sub>RSM</sub>	V <sub>RRM</sub>	I <sub>FRMS</sub> = 200 A (maximum value for continuous operation)		
V	V	I <sub>FAV</sub> = 115 A (sin. 180; T <sub>c</sub> = 83 °C)		
1200	1200	SKKD 115F12		
1400	1400	SKKD 115F14		

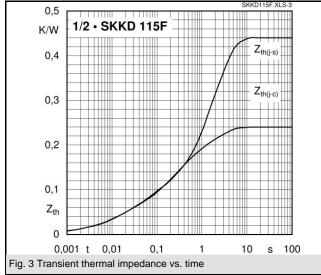
Symbol	Conditions	Values	Units
I <sub>FAV</sub>	sin. 180; T <sub>c</sub> = 85 (100) °C	113 (83)	А
I <sub>FSM</sub>	T <sub>vi</sub> = 25 °C; 10 ms	2500	Α
	T <sub>vi</sub> = 130 °C; 10 ms	2100	Α
i²t	T <sub>vj</sub> = 25 °C; 8,3 10 ms	31250	A²s
	T <sub>vj</sub> = 130 °C; 8,3 10 ms	22000	A²s
V <sub>F</sub>	T <sub>vi</sub> = 25 °C; I <sub>F</sub> = 300 A	max. 1,8	V
V <sub>(TO)</sub>	T <sub>vj</sub> = 130 °C	max. 1,1	V
r <sub>T</sub>	$T_{vj} = 130 \ ^{\circ}C$	max. 2	mΩ
I <sub>RD</sub>	$T_{vj} = 25 \text{ °C}; V_{RD} = V_{RRM}$	max. 1	mA
I <sub>RD</sub>	T <sub>vj</sub> = 130 °C; V <sub>RD</sub> = V <sub>RRM</sub>	max. 30	mA
Q <sub>rr</sub>	T <sub>vi</sub> = 130 °C, I <sub>F</sub> = 100 A,	90	μC
I <sub>RM</sub>	-di/dt = 50 A/μs, V <sub>R</sub> = 30 V	90	А
t <sub>rr</sub>		2000	ns
E <sub>rr</sub>		1,35	mJ
R <sub>th(j-c)</sub>	per diode / per module	0,24 / 0,12	K/W
R <sub>th(c-s)</sub>	per diode / per module	0,2 / 0,1	K/W
T <sub>vj</sub>		- 40 + 130	°C
T <sub>stg</sub>		- 40 + 125	°C
V <sub>isol</sub>	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 / 3000	V~
Ms	to heatsink	5 ± 15 %	Nm
M <sub>t</sub>	to terminals	3 ± 15 %	Nm
а		5 * 9,81	m/s²
m	approx.	120	g
Case		A 10	

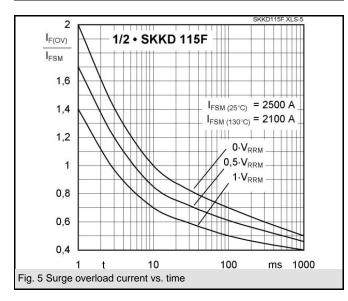


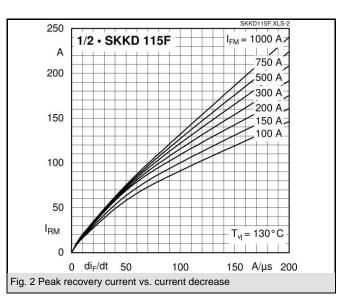
29-06-2009 DIL

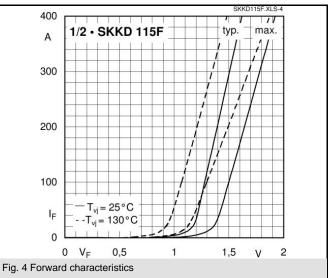
#### DDE, I H I RISTOR, MOD



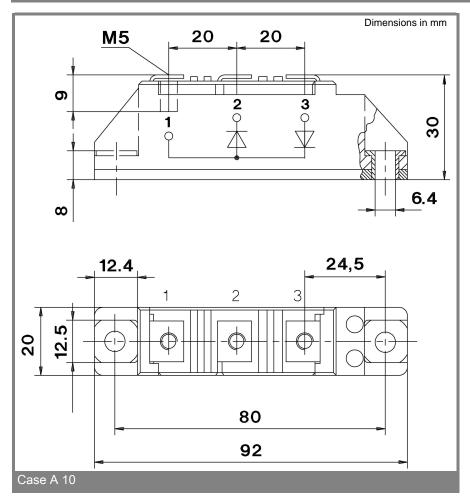








# **SKKD 115F**



This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.